MITSUI
KINZOKU

August 21, 2025

NEWS RELEASE

Enhanced Production Capacity for Ultra-Thin Embedded Capacitance Materials “FaradFlex®”

\- One point six times the Production Capacity up at two manufacturing locations: Malaysia and Japan -

Mitsui Mining & Smelting Co., Ltd. (President: NOU Takeshi) announces that we have successfully completed the enhancement of production capacity and the establishment of a Business Continuity Plan (BCP) for our thin embedded capacitor material "FaradFlex®," which is manufactured at our Malaysia factory (Mitsui Copper Foil (Malaysia) SDN.BHD.) and the Ageo Plant, as stated in our news release dated July 28, 2022, "Enhancement of Production Capacity and Establishment of BCP for Thin Embedded Capacitor Materials."
Furthermore, we are planning to increase the current production capacity by approximately 1.6 times by March 2026.

FaradFlex® is positioned as a growth business following our ultra-thin copper foil MicroThin™ and electrolytic copper foil VSP™ for high-frequency substrates. FaradFlex® is used as a material to reduce communication noise, which is a significant challenge in the pursuit of faster and higher-capacity information and communication devices. It is utilized in high-performance routers, server equipment, high-layer-count substrates for supercomputers, and MEMS microphones embedded in smartphones.

Currently, demand for our products is rapidly increasing due to the rising adoption rates in AI infrastructure, smartphones, and wireless headsets. Given the anticipated market growth, we have decided to enhance the production capacity at both our Malaysia factory and Ageo Plant, which are the production factories for FaradFlex®.

Latest combined production capacity of our two-factories at the Malaysia plant and the Ageo plant has been increased to approximately 2.2 times the 2022 level. Additionally, we will continue to expand production facilities and further improve productivity with existing equipment, aiming to enhance our production capacity to approximately 1.6 times the current level (approximately 3.5 times the 2022 level) by March 2026.

We will continue to consider further capacity up to meet the growing demand and committed to fully responding to the expected strong demand.

Mitsui Kinzoku will contribute to the realization of a sustainable society by implementing our its vision for 2030, “Building new businesses -and the future- with our material intelligence,” based on its purpose, “We promote the well-being of the world through a spirit of exploration and diverse technologies.”

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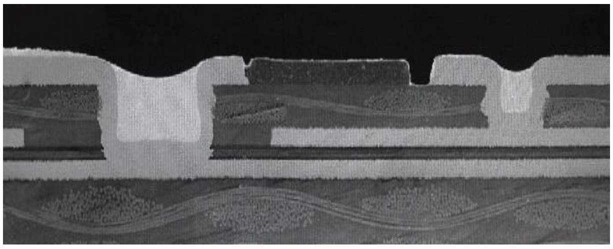
[Reference]

1. Manufacturing FaradFlex®

FaradFlex® is a material that is composed of ultra-thin dielectric layer (thickness range of 3 to 25 um) with a copper foil on both sides (with a typical thickness range of 18 to 70 µm).

FaradFlex® forms a circuit that serves as a capacitor embedded in the PCB.

Cross section of PCB incorporating FaradFlex®

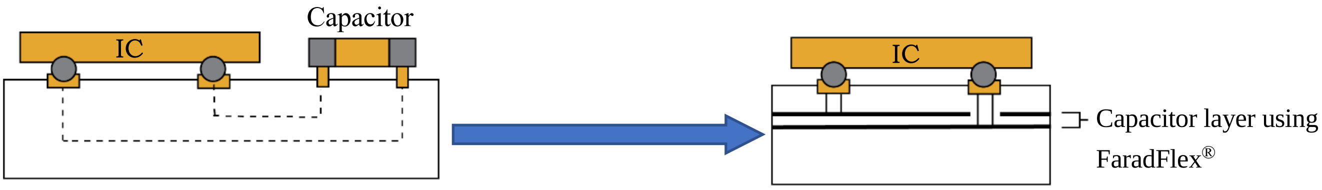


FaradFlex® (Three-layer structure of copper foil, dielectric layer, and copper foil)

2. An example of the simulated use of an embedded capacitor

FaradFlex® allows a capacitor layer to be formed immediately below the IC.

Communication noise can be reduced by shortening the distance between the IC and the capacitor layer.



FaradFlex® embedded in a PCB